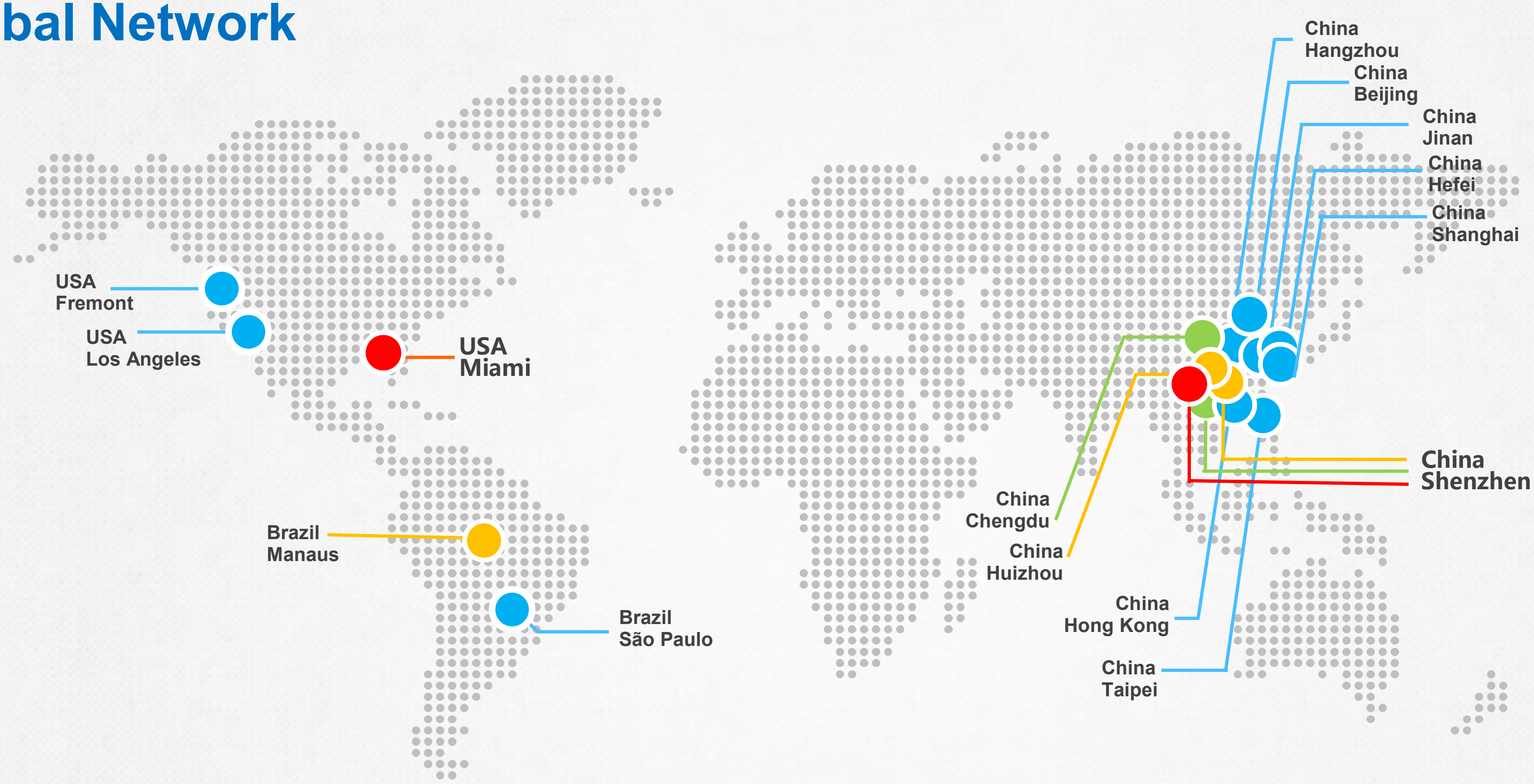
Company Profile

BIWIN STORAGE TECHNOLOGY CO., LTD.

About BIWIN

- Founded in **1995**, headquarter in Shenzhen, China
- **25** years R&D in storage and micro electronics
- **12"** wafer packaging factory of Biwin built in 2009
- **11,000m²** total area of the factory
- **1K** level Dust-free workshop
- **800** staff around, multiple patents of storage core technology, self-developed software and hardware, firmware development, storage algorithm as well as craft development.
- **3** types of product & service: Storage, IOT Module, Wafer Packaging
- **One-stop service**: Circuit Design, ID Design, Module Design, Software Development, Application Development, Wafer Packaging and Testing, Turnkey Solution (Total solution).

About BIWIN
Global Network



🟥 Headquarter

Global Headquarter: Shenzhen
America Headquarter : Miami

🟩 R&D center × 2

Shenzhen、Chengdu

🟨 Production location × 3

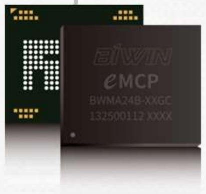
Shenzhen、Huizhou、Manaus

Overview Of BIWIN Embedded Products

R/D、Qualification、Assembly、Testing、SMT、Wafer PKG

eMMC

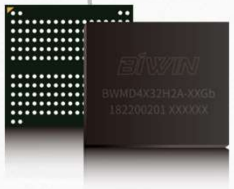
Smart phone、Tablet、GPS、Smart TV、 OTT



eMCP

Digital learning machine、Video game player,

Smart phone

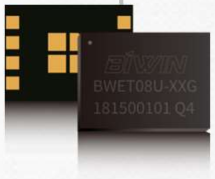


LPDDR

Mobile phone、Tablet、GPS、Smart TV

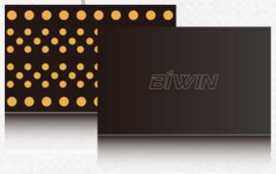
BGA SSD

Ultrabook、2-in-1 Laptop、tablet、Small form factor PC、Smart TV



SPI NAND

OTT、Optical modem、TV set-top box



cNAND

USB drive、Solid state drive

Overview Of BIWIN SSD

R/D、Qualification、Assembly、Testing、SMT、Wafer PKG

Industrial Storage

Monitor 、 Medical equipment 、 NC machine、 Industrial Computer、 ATM、 POS

Enterprise Storage

Data analysis and storage、 Media stream、 Server 、Image and video workstation

Client Storage

Laptop 、 Desktop 、All-in-one PC

Electronic Sports

Gaming Laptop、Gaming Desktop

Portable SSD

Business man、Mobile Office

Customized SSD

We can provide customized service for SSD

R&D Capability Capability

Firmware R&D

FW Front End

- Custom script testing of Test Metrix
- Adjust Front-end protocol (eMMC) process for different host platform compatibility
- Meet the front-end protocol testing requirement of eMMC 5.0

FTL

- Develop production level Independent FTL codes
- Custom FTL algorithm and architecture for different industry customers
- Fully support the script test requirements

CTL

- Quickly import various new 2D or 3D Flash; achieve MP within 1~1.5 months.
- Independent flash feature analysis team; Adjust FTL and CTL algorithm according to the analytic results of different NAND flash

MP TOOL and Self-Test FW

- Adjust mass production aging process according to different Flash features
- Advanced pilot production aging test platform and terminal customer test platform

OTA and REMP

- Complete process of OTA and REMP
- Process of debug & rework

Production-Manufacturing Capability

Factory Introduction

2009 year of fundation, Shenzhen base
Factory Areas : 12,042 square meters
Product line: embedded memory chip, USB storage module, memory card, solid state drive, package testing

	Solid State Drives (Monthly)	Flash (Monthly)	Embedded Chip (Monthly)	Package & Testing (Monthly)
SHENZHEN	350K	2M	5M	7M

New Factory Facility (Q3/2021)

New R&D center and manufacturing based in Huizhou
Factory Areas : 110,000 m²
Production line: embedded memory chip, USB storage module, memory card, solid state drive, package testing

	Solid State Drives (Monthly)	Flash (Monthly)	Embedded Chip (Monthly)	Package & Testing (Monthly)
HUIZHOU	1.5M	20M	15M	40M

Production-Manufacturing Capability

Wafer Packaging Process

Back Grinding

Machine Model

TSK PG300RM

Precision

The wafer can be grinded to 50um thickness, tolerance +/-10um

Die Sawing

Machine Model

TSK AWD-300TXB & Disco DFD6361

Precision

Die Sawing process is to cut the wafer into separate pieces.

Die Bonding

Machine Model

Hitachi DB700

Precision

Tolerance +/-5um

Laser Cutting

Machine Model

HAMIsemiconductor-3000

Precision

Tolerance +/-30um

Molding

Machine Model

Towa Auto Mold Y-1

Precision

Tolerance +/-0.1mm

Wire Bonding

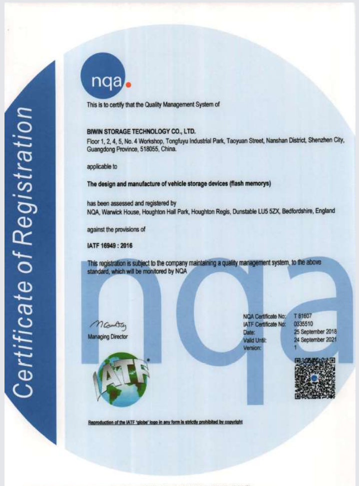
Machine Model

K&S Iconn

Precision

Tolerance +/-5um

BIWIN Quality System
Certifications



Certificate of Registration

This is to certify that the Quality Management System of

BIWIN STORAGE TECHNOLOGY CO., LTD.
Floor 1, 2, 4, 5, No. 4 Workshop, Tongfuyu Industrial Park, Taoyuan Street, Nanshan District, Shenzhen City, Guangdong Province, 518055, China.

applicable to

The design and manufacture of vehicle storage devices (flash memorys)

has been assessed and registered by
NQA, Warwick House, Houghton Hall Park, Houghton Regis, Dunstable LU5 5ZX, Bedfordshire, England

against the provisions of

IATF 16949 : 2016

This registration is subject to the company maintaining a quality management system, to the above standard, which will be monitored by NQA

Managing Director

NQA Certificate No: T 81607
IATF Certificate No: 0335510
Date: 25 September 2018
Valid Until: 24 September 2021
Version: 1

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Issue 5

IATF:16949

证书编号 Certificate No. 561500443001

QG08

认证企业证书

AEO CERTIFICATE

认证企业名称 AEO Name: 深圳佰维存储科技有限公司
认证企业编号 AEO Code: AEOCN4453065733
认证企业类型 AEO Type: 高级认证企业
认证日期 Date of Authorization: 2014 年 12 月 1 日

发证机关 Issuing Authority: 深圳海关
发证日期 Date of Issue: 2015 年 11 月 30 日

AEO CERTIFICATE

IEC QUALITY ASSESSMENT SYSTEM (IECQ)
covering Electronic Components
Assemblies, Related Materials and Processes

IECQ Certificate of Conformity
Hazardous Substance Process Management

BIWIN STORAGE TECHNOLOGY LIMITED

Issued by the Certification body: SGS-CSTC Standards Technical Services Co. Ltd.

SGS

IECQ-CQ 080000

BIWIN STORAGE TECHNOLOGY LIMITED
深圳佰维存储科技有限公司

ISO 9001:2008

ISO9001:2008

sira CERTIFICATION

环境管理体系认证证书

兹证明

深圳佰维存储科技股份有限公司

注册地址：中国广东省深圳市南山区桃源街道同富裕工业城 4 号厂房 1 楼、2 楼、4 楼、5 楼
审核地址：中国广东省深圳市南山区桃源街道同富裕工业城 4 号厂房 1 楼、2 楼、4 楼、5 楼

其环境管理体系已通过 Sira Certification Service 的评审，符合

GB/T24001-2016 idt ISO14001:2015 标准

认证范围

集成电路产品封装、闪存卡的研发、生产和销售

认证经理

Sira Certification Service

ISO14001:2015

SGS

此为证书 CN14/30608 译本

深圳佰维存储科技股份有限公司

中国广东省深圳市
南山区桃源街道同富裕工业城 4 号厂房 1 楼, 2 楼, 4 楼, 5 楼

统一社会信用代码 91440300561500443T

ISO 9001:2015

集成电路的设计与封装;
存储产品的设计与制造

该证书的有效期自 2018 年 07 月 29 日至 2020 年 05 月 21 日
组织必须定期接受监督审核并经审核合格此证书方继续有效
持续认证至少在证书失效前 60 天执行
版本号 3. 初始注册日期 2014 年 05 月 21 日

SGS United Kingdom Ltd
Rossmore Business Park Ellesmere Port Cheshire CH65 3 EN UK

ISO9001:2015

QCO80000/ISO14001/ISO9001/BSCI/AEO

We passed the validation of IATF:16949 in 2018

Solid State Drive

Bright Spots of BIWIN SSD

Global Exclusive Brand Licensee

By positioning of High-end mark, we are widely accepted by customers and recognized by authorities. The Portable SSD P800 achieved CES 2018 Innovation Awards.

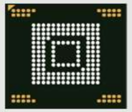
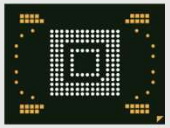
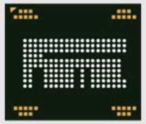
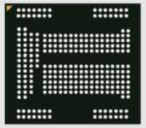
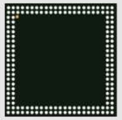
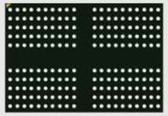
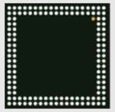
Storage for Special Usage

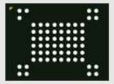
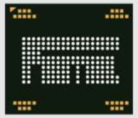
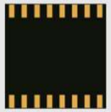
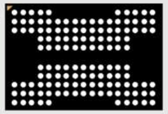
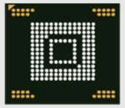
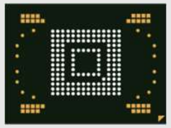
1. **Special Field.** High-end Storage for military. Applied to Many special storage research and development projects.
2. **Financial Terminal Field.** Supplied to more than 300,000 POS Machines, ATM Machines and other high-reliability storage equipment.
3. **Vehicle-mounted Field.** Served for nearly 100,000 vehicles , and applied to High-speed train monitoring, train monitoring, bus monitoring and other mobile monitoring)

BGA SSD and Other New SSD Product Development

Embedded SSD Products, High speed, Thin

Embedded Product form factor

Product	**eMMC**				**eMCP**			**LPDDR**				**ePOP**
Photo												
Size(mm)	8.0×8.0	9.0×11.0	11.5×13.0	12.0×16.0 14.0*18.0	11.5×13.0	11.5×13.0 11.66×13.16	11.5×13.0 11.5X14.5	11.5×11.0	12.0×12.0	11.5×14.5	10.0×14.5	10.0×10.0
Package	LFBGA153	LFBGA153	LFBGA153	LFBGA169	LFBGA162	LFBGA221	BGA254	LFBGA178	LFBGA168	LFBGA254	LFBGA200	LFBGA136

Product	**RAW NAND**		**nMCP**		**SPI NAND**		**DMMC**			**UFS**	
Photo											
Size(mm)	9.0×11.0	12.0×20.0	8.0×10.5	11.5×13.0	6.0×8.0	10.3×10.6	9.0×11.00 (Controller)	12.0×20.0 (FLASH)	12.0×20.0 (FLASH)	11.5×13.0	12.0×16.0
Package	LFBGA63	TSOP48	LFBGA162	LFBGA162	LGA 8	LGA 16	LFBGA153	BGA132	TSOP48	LFBGA153	LFBGA169

Market and Sales

Embedded Product

NAND

Controller

R/D
Qualification
Assembly
Testing
SMT
PKG

eMMC
Smart phone、Tablet、GPS、Smart TV, OTT

eMCP
Digital learning mahine、Gaming machine, Smart Phone

LPDDR
Mobile phone、Tablet、GPS、Smart TV

BGA SSD
Ultrabook、2-in1s Laptop、Tablet、Small Form Factor PC、Smart TV

SPI NAND
Smart phone、Tablet、GPS、Smart TV, OTT

cNAND
USB Drive、
Solid State Drive

Embedded Memory Chip

Bright Spots of Memory Chip

STB(Set Top Box)

Deep into China mobile set-top box market, We are STB certificated original factory and the only one domestic investment Nand Flash factory.

Our annually supply of memory chips which covers nearly 20% market share. Main partner:UNIONM AN、YSTEN , Xingfei, TwoWin.

中国移动 China Mobile

九联科技 UNIONMAN

Smart Phone

With the increasing shipments to smart phone customers, our customer structure is improving. We are one of the few domestic memory chip manufacturers which can break into tier 2 mobile phone supply chain. We are stepping into Tier 1 supply chain.

TRANSSION 传音控股 HQ华勤通讯 ZTE中兴

WINGTECH PROFESSIONAL SOLUTIONS TCL CNCE中诺通讯

Intelligent Speakers, watches, etc

The shipments to intelligent terminals , such as intelligent Speakers, Smart watch、Smart stracker and so on are growing rapidly.

facebook fitbit

Baidu百度 小天才 读书郎

Vehicle-mounted and Internet of Things

We will focus on Internet of things and on-board electronics in our future development. We continuously supplies to Internet of things module manufacturers. We had passed the vehicle certification and began the supply.

FlyAudio飞歌 uniview宇视科技

alhua TECHNOLOGY

BIWIN Strengths

Specialization

Focused on development of flash and related software products for 25 years; Relying on its leading encapsulation technology, BIWIN actively promotes storage technology and SIP to business promotion and application

Technology Advantage

Founded in 2009 with its own perfect 12’ ’ wafer packaging factory, BIWIN has put huge investment and energy to expand semiconductor packaging enterprise in the south of China

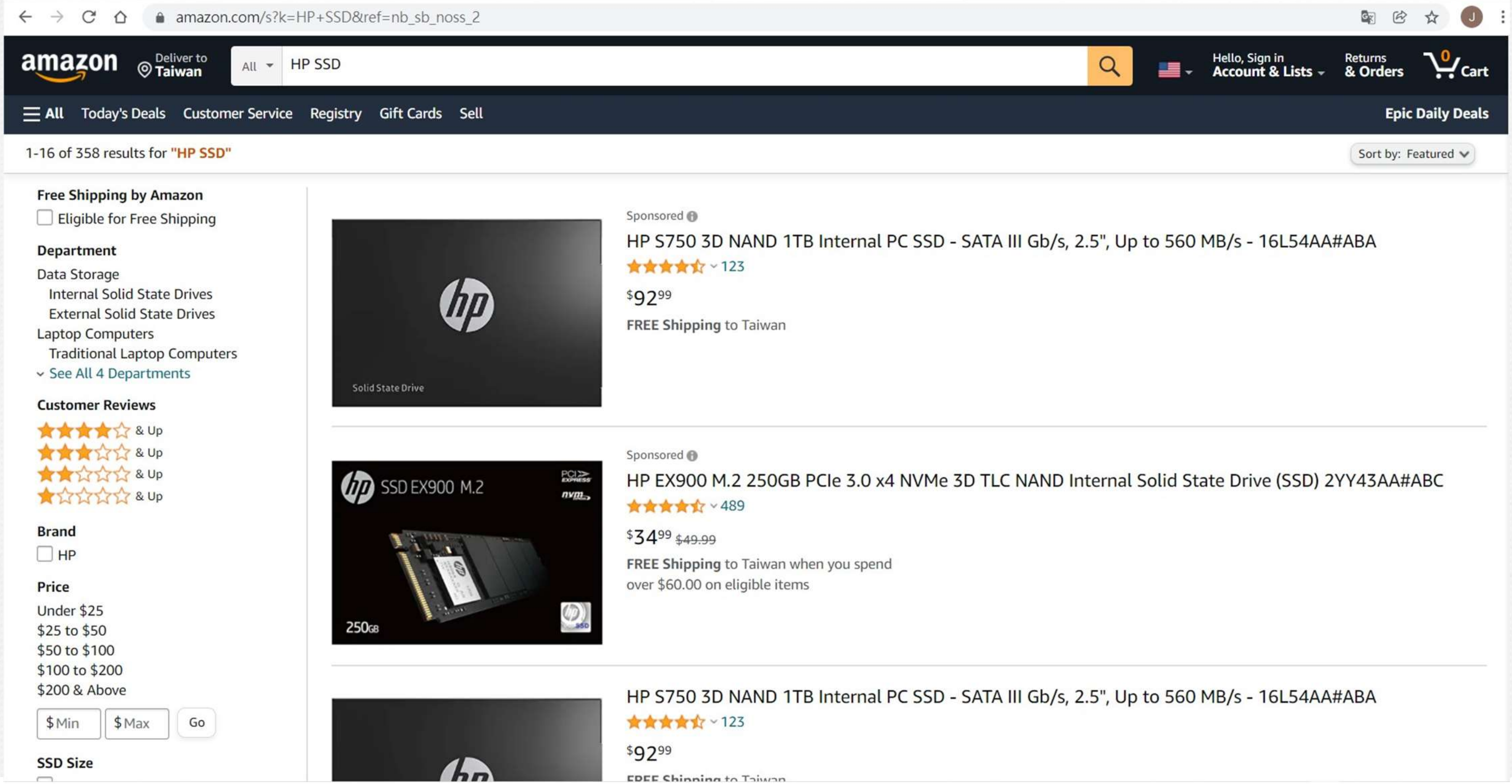
Quick Response

With the joint efforts of marketing team and R&D team, BIWIN constantly analyses the trend of the market, product development and customization service innovation, responses to market and customer requirements rapidly

Win-win Philosophy

Our core advantages are packaging & testing services and industry resource integration for hardware cooperations in the field of micro electronics. BIWIN is willing to work with customers on the principle of complementary advantages to develop new cooperation for storage industry

Appendix



amazon.com/s?k=HP+SSD&ref=nb_sb_noss_2

HP SSD

1-16 of 358 results for "HP SSD"

Free Shipping by Amazon

☐ Eligible for Free Shipping

Department

Data Storage
  Internal Solid State Drives
  External Solid State Drives
Laptop Computers
  Traditional Laptop Computers
See All 4 Departments

Customer Reviews

★★★★☆ & Up
★★★☆☆ & Up
★★☆☆☆ & Up
★☆☆☆☆ & Up

Brand

☐ HP

Price

Under $25
$25 to $50
$50 to $100
$100 to $200
$200 & Above

$Min $Max Go

SSD Size

Sponsored

HP S750 3D NAND 1TB Internal PC SSD - SATA III Gb/s, 2.5", Up to 560 MB/s - 16L54AA#ABA

★★★★☆ 123

$92.99

FREE Shipping to Taiwan

Sponsored

HP EX900 M.2 250GB PCIe 3.0 x4 NVMe 3D TLC NAND Internal Solid State Drive (SSD) 2YY43AA#ABC

★★★★☆ 489

$34.99 ~~$49.99~~

FREE Shipping to Taiwan when you spend over $60.00 on eligible items

HP S750 3D NAND 1TB Internal PC SSD - SATA III Gb/s, 2.5", Up to 560 MB/s - 16L54AA#ABA

★★★★☆ 123

$92.99

THANKS!

BIWIN STORAGE TECHNOLOGY CO., LTD.

www.biwin.com.cn